

**AMENDMENTS TO THE CLAIMS**

1. (Currently amended)      A method for manufacturing a substrate with a plasma processing system, the method comprising:

obtaining a component of a plasma processing system which has been coated with a film of material;

disposing said component in a first plasma processing chamber;

disposing a substrate on a chuck in the first plasma processing chamber; and

forming a first plasma in a processing region within the first plasma processing chamber, wherein the film of material has been coated using a second plasma in a second plasma processing chamber different from said first plasma processing chamber; ~~and wherein the chemistries of the first and second plasmas are substantially the same.~~

2. (Original)    The method for manufacturing a substrate with a plasma processing system as recited in claim 1, wherein the obtaining includes obtaining a component from one of a component manufacturer and plasma processing chamber manufacturer.

3.-4. (Cancelled)

5. (Previously presented)      The method for manufacturing a substrate with a plasma processing system as recited in claim 1, wherein the second plasma processing chamber used to coat the component is similar to the first plasma processing chamber where the substrate is disposed.

6. (Original) The method for manufacturing a substrate with a plasma processing system as recited in claim 1, wherein the film of material comprises a minimum thickness determined by at least one of a customer specification, a supplier specification, a process recipe, a chamber parameter, a pre-seasoning time, and a type of process used to manufacture the substrate.

7. (Original) The method for manufacturing a substrate with a plasma processing system as recited in claim 1, wherein the film of material comprises a uniformity determined by at least one of a customer specification, a supplier specification, a process recipe, a chamber parameter, a pre-seasoning time, and a type of process used to manufacture the substrate.

8. (Previously presented) The method for manufacturing a substrate with a plasma processing system as recited in claim 1, wherein the film of material comprises a material that is determined by at least one of a customer specification, a supplier specification, a process recipe, a chamber parameter, a pre-seasoning time, and type of process used to manufacture the substrate.

9. (Original) The method for manufacturing a substrate with a plasma processing system as recited in claim 1, wherein the film of material has a thickness within a range of about 1 to about 500 microns.

10. (Cancelled)

11. (Original) The method for manufacturing a substrate with a plasma processing system as recited in claim 1, further comprising pumping excess gas through a pump opening arranged in the plasma processing chamber.

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12. (Original) The method for manufacturing a substrate with a plasma processing system as recited in claim 11, wherein:

the obtaining includes obtaining a pumping deposition shield that has been coated with a film of material; and

the component disposing includes disposing said pumping deposition shield in the pump opening.

13.-31. (Withdrawn)